NAPA ECHLIN®

Did You Know?

NAPA Echlin D.I.S. Modules have "Added Value"

NAPA Echlin Modules use double wire bonds to connect the lead to the substrate.
Advantage: Double insurance against failure from heat and vibration. Reduced voltage drop in circuit.

NAPA Echlin Modules use a copper header under the Power Darlington transistor.
Advantage: Improved heat dissipation.
The Competition: Competitor uses single wire bonding – increased risk of failure due to broken connection and more voltage drop in circuit. Competitor uses two control I/Cs separating the logic and power circuits – old technology.

NAPA Echlin's exclusive design incorporates the original equipment IC "Flip Clip".
Advantage: NAPA Echlin is the only aftermarket EM DIS manufacturer that can match OE.

NAPA Echlin features voltage spike protection within the Power Darlington Transistor. Competitor features voltage spike protection external to the Power Darlington Transistor .
Advantage: Improved voltage spike protection, longer life.

NAPA Echlin uses an MOV (Metal Oxide Varistor) and a separate voltage regulator featuring internal over-voltage protection.
Advantage: Reduces failure due to voltage spikes.

NAPA Echlin features a shiny, crisp appearance of the molded surface.
Advantage: Prevents foreign matter from adhering to surface. Easy application to connectors during removal and diagnosis.

NAPA Echlin modules incorporate many features that improve the O.E. design.

The Competition

- No copper header.
  Limits heat dissipation.
- Competitor uses single wire.
  More susceptible to voltage drop.
- Competitor features two control I/Cs, separating digital from analog processing.
- Older technology.

NAPA Echlin Modules
LOOKS RIGHT. FITS RIGHT. PERFORMS RIGHT.

THE BEAR IS BACK ECHLIN®

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